Heat Sinks Feature Push Pin Mounting

Advanced Thermal Solutions, Inc. (ATS) now provides maxiFLOW™ heat sinks with an integral push pin mounting system for fast, safe attachment of the heat sinks onto BGAs and other hot components
Each heat sink comes with a pair of durable plastic or brass push. The pins run through opposite corners of the heat sinks and mount securely into 3.00 mm holes in the PCB laid out in industry standard patterns. Plastic pins are lighter and non-electrically conductive; brass pins have added strength and durability for more rugged applications or thicker devices. An integral spring on each pin provides approximately 2 lbs of retention load, depending on the height of the component and the PCB thickness.

The patented ATS maxiFLOW sinks feature a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling in the restricted airflow conditions typical of today’s condensed electronic packages. The heat sinks are fabricated from light weight, extruded aluminum which minimizes thermal resistance from the base to the fins. They have a protective green anodized surface.

Tests on maxiFLOW heat sinks with an airflow rate of just 100 lfm (linear feet per minute) show that device junction temperatures (Tj) can be reduced by more than 40 percent below the temperatures achieved using conventional straight-fin heat sinks.

The push pin mount maxiFLOW heat sinks are available in sizes ranging from 37.4 x 37.5 x 10.0 mm (L x W x H) up to 41.4 x 45.75 x 24.5 mm (L x W x H). Each maxiFLOW heat sink is provided preassembled with a Chomerics T766 phase change thermal interface material (TIM) for improved component-to-sink thermal transfer. The pad is centered on the base of the sink.

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